

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination LEE ET AL.	
		Examiner	Art Unit	Page 1 of 1
		Thomas J. Magee	2811	

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	B	US-6,084,295	07-2000	Horiuchi et al.	257/690
	C	US-6,620,720 B1	09-2003	Moyer et al.	438/612
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NON-PATENT DOCUMENTS

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	V	Electronic Packaging and Production, "Innovative PCB Reinforcement," (February, 1997), p.1
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.